



## Correction: Droplet microfluidics: fundamentals and its advanced applications

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In addition, the authors regret that incorrect reference numbers were given in Table 1 of the original article. The corrected table and references are shown below.

The Royal Society of Chemistry apologises for these errors and any consequent inconvenience to authors and readers.

**Table 1** Size and frequency distributions for various droplet generation systems

	Geometry and material	Continuous phase	Size/ $\mu\text{m}$	Frequency/ Hz	Ref. in original article reference list	Ref. in this Correction
Water in oil	Channel array in silicon	Kerosene with monolaurate	21	~5300 (est.)	—	1
	T-junction in acrylated urethane	Decane, tetradecane, and hexadecane with Span 80	10 to 35	20 to 80	—	2
	T-junction in PMMA	High oleic sunflower oil	100 to 350	10 to 2500	—	3
	T-junction in PDMS	$\text{C}_{14}\text{F}_{12}$ with $(\text{C}_6\text{F}_{13})(\text{CH}_2)_2\text{OH}$	7.5 nl (plug flow)	2	55	4
	Shear-focusing in PDMS	Oleic acid	13 to 35 (satellites <100 nm)	15–100	49	5
Oil in water	Channel array in silicon	Water with SDS	22.5	~5300 (est.)	—	1
	Sheath flow in glass capillary	Water with SDS	2 to 200	100 to 10 000	—	6
Gas in liquid	Flow-focusing in PDMS	Water with Tween 20	10 to 1000	>100 000	—	7
	Shear-focusing in PDMS	Water with phospholipids	5 to 50	>1 000 000	—	8
Liquid in air	DEP on hydrophobic insulator	Air	10 pl	~8 (est.)	57	9
	EWOD on hydrophobic insulator	Air	~700 nl	~1 (est.)	28	10



## References

- 1 T. Kawakatsu, Y. Kikuchi and M. Nakajima, *J. Am. Chem. Soc.*, 1997, **74**, 317–321.
- 2 T. Thorsen, R. W. Roberts, F. H. Arnold and S. R. Quake, *Phys. Rev. Lett.*, 2001, **86**, 4163–4166.
- 3 T. Nisisako, T. Torii and T. Higuchi, *Lab Chip*, 2002, **2**, 24–26.
- 4 W. H. Wang, Z. L. Zhang, Y. N. Xie, L. Wang, S. Yi, K. Liu, J. Liu, D. W. Pang and X. Z. Zhao, *Langmuir*, 2007, **23**, 11924–11931.
- 5 Y. C. Tan, V. Cristini and A. P. Lee, *Sens. Actuators, B*, 2006, **114**, 350–356.
- 6 P. B. Umbanhowar, V. Prasad and D. A. Weitz, *Langmuir*, 2000, **16**, 347–351.
- 7 P. Garstecki, I. Gitlin, W. DiLuzio, G. M. Whitesides, E. Kumacheva and H. A. Stone, *Appl. Phys. Lett.*, 2004, **85**, 2649–2651.
- 8 K. Hettiarachchi, E. Talu, M. L. Longo, P. A. Dayton and A. P. Lee, *Lab Chip*, 2007, **7**, 463–468.
- 9 R. Ahmed and T. B. Jones, *J. Electrostat.*, 2006, **64**, 543–549.
- 10 M. G. Pollack, A. D. Shenderov and R. B. Fair, *Lab Chip*, 2002, **2**, 96–101.

